



PROCIRC 9977

Hot Air Levelling Flux

INTRODUCTION

Procirc 9977 is a heat stable organic flux used in vertical hot air levelling.

It is water soluble, non-foaming and is easily removed by rinsing the printed circuit boards in water.

Procirc 9977 shows very little carbonisation.

BENEFITS

- Non-drying, therefore blanketing the molten solder to prevent re-oxidation as well as preventing solder balls sticking to the solder mask or laminate.
- First time coverage of difficult SMD pads.
- High SIR-values better than 10^{10} Ohm can be obtained in vertical HAL
- Complete edge coverage.
- Low copper dissolution
- Biodegradable.

SOLUTION CHARACTERISTICS

Specific Gravity (25°C)	1.1g/cm ³
Viscosity (25°C)	280cps
Flash Point (COC)	300°C

EQUIPMENT

Can be used in dip or roller applications.

INSTALLATION

It is essential that the tanks to be used for Procirc 9977 HAL Flux are thoroughly cleaned before any chemistry is introduced.

Contact PMD Technical Department for appropriate procedure.

PROCESS SEQUENCE

1. Microetch in Procirc 921, 923 or SP263 Microetch.
2. Rinse.
3. Dry (Preferable).
4. Procirc 9977 Hot Air Levelling Flux application (roller or dip).
5. Solder level.
6. Wash off.
7. Dry.

MAINTENANCE AND CONTROL

Under optimum processing conditions it is not necessary to carry out analytical maintenance and control in order to maintain the performance of this product.

DISPOSAL

Dispose of in accordance with Local Authority requirements.

PRODUCT FAMILIES

The following products are referred to in this data sheet.

PRODUCT NAME	PRODUCT NUMBER
Procirc 9977 Hot Air Levelling Flux	997025
Procirc 921 Microetch	923001
Procirc 923 Microetch	927001
Procirc SP263 Microetch	923003

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